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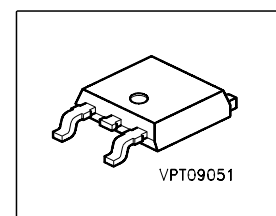
sales@integrated-circuit.com


IDD06E60
Fast Switching EmCon Diode
Product Summary

V_{RRM}	600	V
I_F	6	A
V_F	1.5	V
T_{jmax}	175	°C

Feature

- 600 V EmCon technology
- Fast recovery
- Soft switching
- Low reverse recovery charge
- Low forward voltage
- 175°C operating temperature
- Easy paralleling
- Pb-free lead plating; RoHS compliant
- Qualified according to JEDEC⁰⁾ for target applications



Type	Package	Ordering Code	Marking	Pin 1	PIN 2,4	PIN 3
IDD06E60		-	D06E60	NC	C	A

Maximum Ratings, at $T_j = 25\text{ °C}$, unless otherwise specified

Parameter	Symbol	Value	Unit
Repetitive peak reverse voltage	V_{RRM}	600	V
Continuous forward current $T_C = 25\text{ °C}$ $T_C = 90\text{ °C}$	I_F	14.7 10	A
Surge non repetitive forward current $T_C = 25\text{ °C}$, $t_p = 10\text{ ms}$, sine halfwave	I_{FSM}	29	A
Maximum repetitive forward current $T_C = 25\text{ °C}$, t_p limited by $t_{j,max}$, $D = 0.5$	I_{FRM}	22	A
Power dissipation $T_C = 25\text{ °C}$ $T_C = 90\text{ °C}$	P_{tot}	46.8 26.6	W
Operating junction temperature	T_j	-40...+175	°C
Storage temperature	T_{stg}	-55...+150	
Soldering temperature 1.6mm (0.063 in.) from case for 10 s	T_S	260	


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Thermal Characteristics

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
Characteristics					
Thermal resistance, junction - case	R_{thJC}	-	-	3.2	K/W
SMD version, device on PCB:	R_{thJA}				
@ min. footprint		-	-	75	
@ 6 cm ² cooling area ¹⁾		-	-	50	

Electrical Characteristics, at $T_j = 25\text{ }^\circ\text{C}$, unless otherwise specified

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
Static Characteristics					
Reverse leakage current	I_R				μA
$V_R=600\text{V}, T_j=25\text{ }^\circ\text{C}$		-	-	50	
$V_R=600\text{V}, T_j=150\text{ }^\circ\text{C}$		-	-	500	
Forward voltage drop	V_F				V
$I_F=6\text{A}, T_j=25\text{ }^\circ\text{C}$		-	1.5	2	
$I_F=6\text{A}, T_j=150\text{ }^\circ\text{C}$		-	1.5	-	

⁰J-STD20 and JESD22

¹Device on 40mm*40mm*1.5mm epoxy PCB FR4 with 6cm² (one layer, 70 μm thick) copper area for drain connection. PCB is vertical without blown air.


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Electrical Characteristics, at $T_j = 25\text{ °C}$, unless otherwise specified

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
Dynamic Characteristics					
Reverse recovery time	t_{rr}				ns
$V_R=400V, I_F=6A, di/dt=550A/\mu s, T_j=25\text{ °C}$		-	70	-	
$V_R=400V, I_F=6A, di/dt=550A/\mu s, T_j=125\text{ °C}$		-	100	-	
$V_R=400V, I_F=6A, di/dt=550A/\mu s, T_j=150\text{ °C}$		-	105	-	
Peak reverse current	I_{rrm}				A
$V_R=400V, I_F=6A, di/dt=550A/\mu s, T_j=25\text{ °C}$		-	6.5	-	
$V_R=400V, I_F=6A, di/dt=550A/\mu s, T_j=125\text{ °C}$		-	7.4	-	
$V_R=400V, I_F=6A, di/dt=550A/\mu s, T_j=150\text{ °C}$		-	7.9	-	
Reverse recovery charge	Q_{rr}				nC
$V_R=400V, I_F=6A, di/dt=550A/\mu s, T_j=25\text{ °C}$		-	240	-	
$V_R=400V, I_F=6A, di/dt=550A/\mu s, T_j=125\text{ °C}$		-	360	-	
$V_R=400V, I_F=6A, di/dt=550A/\mu s, T_j=150\text{ °C}$		-	400	-	
Reverse recovery softness factor	S				
$V_R=400V, I_F=6A, di_F/dt=550A/\mu s, T_j=25\text{ °C}$		-	4	-	
$V_R=400V, I_F=6A, di_F/dt=550A/\mu s, T_j=125\text{ °C}$		-	4.8	-	
$V_R=400V, I_F=6A, di_F/dt=550A/\mu s, T_j=150\text{ °C}$		-	4.9	-	

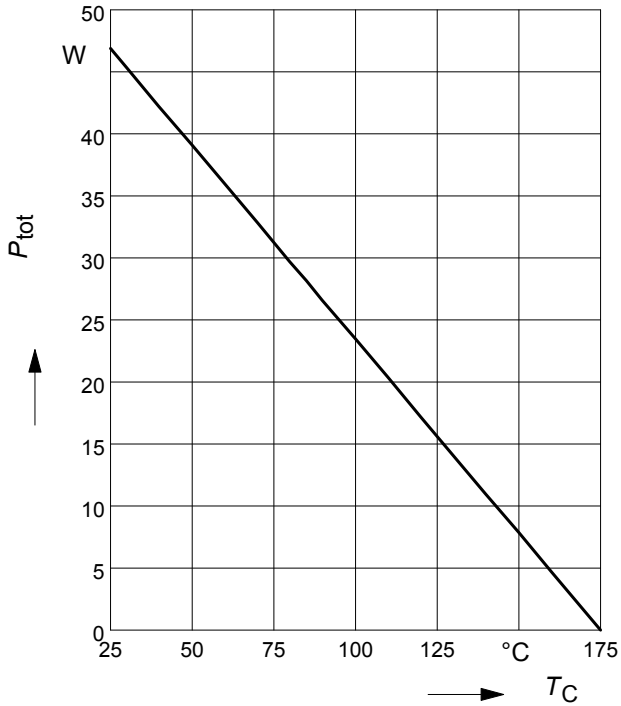


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1 Power dissipation

$$P_{\text{tot}} = f(T_C)$$

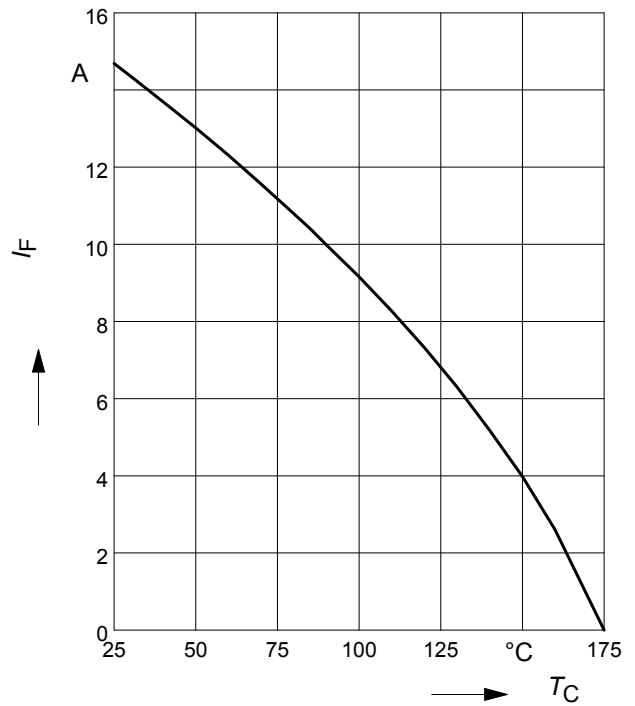
parameter: $T_j \leq 175^\circ\text{C}$



2 Diode forward current

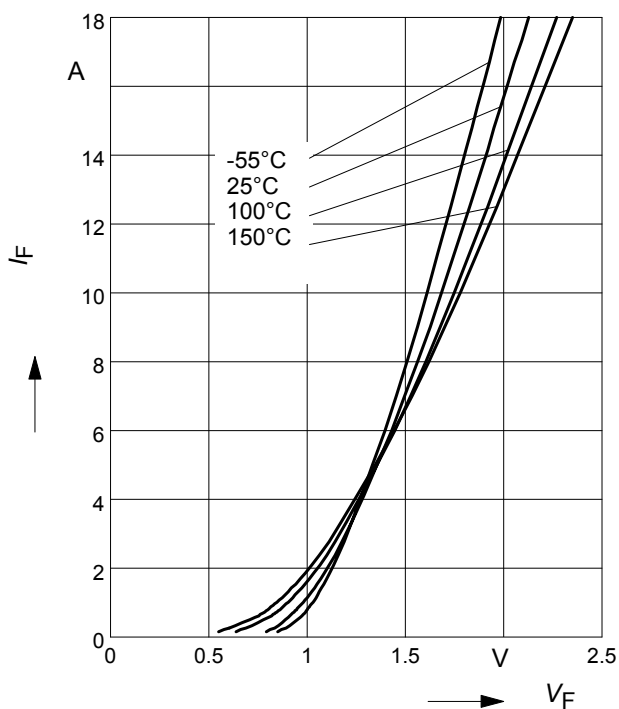
$$I_F = f(T_C)$$

parameter: $T_j \leq 175^\circ\text{C}$



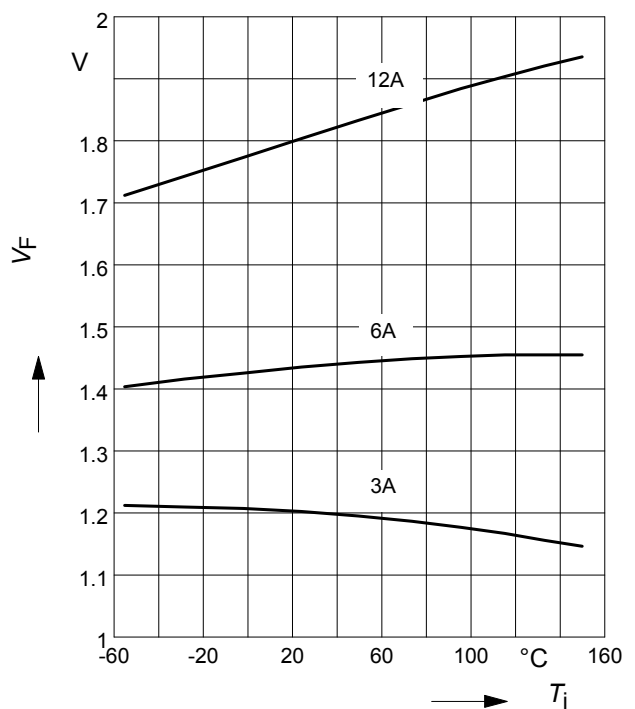
3 Typ. diode forward current

$$I_F = f(V_F)$$



4 Typ. diode forward voltage

$$V_F = f(T_j)$$



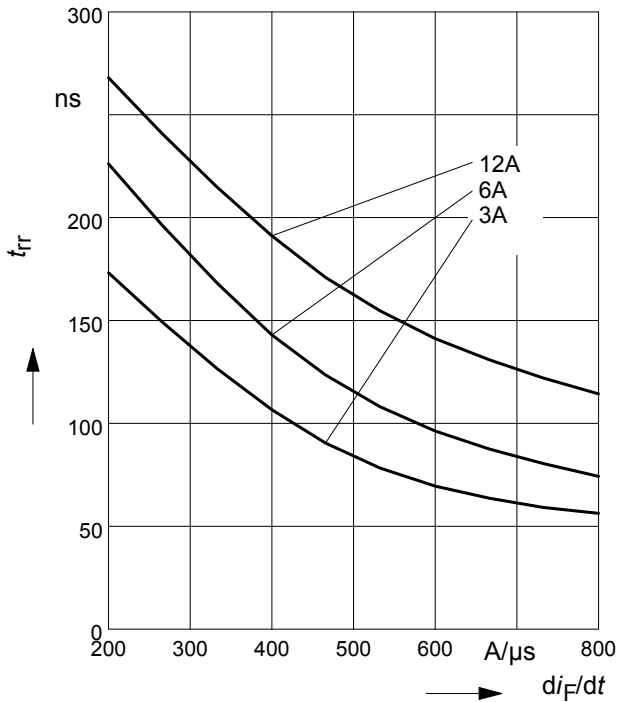


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5 Typ. reverse recovery time

$t_{rr} = f(di_F/dt)$

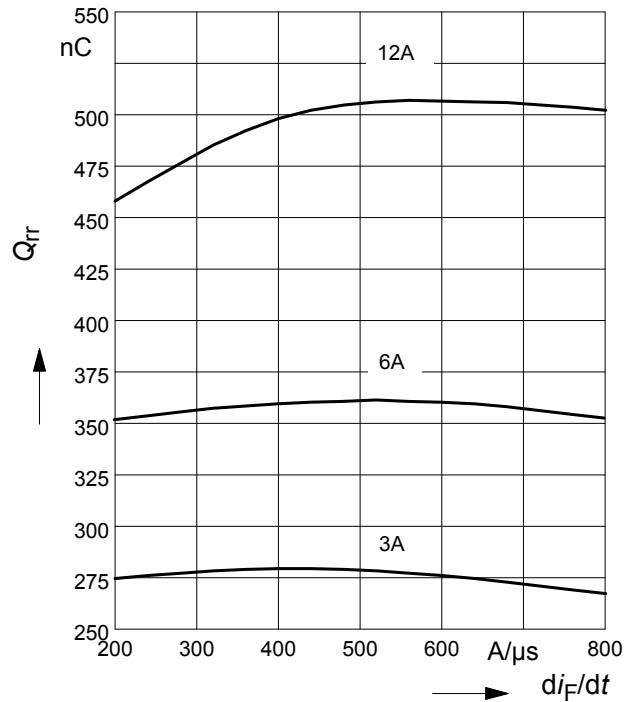
parameter: $V_R = 400V, T_j = 125^\circ C$



6 Typ. reverse recovery charge

$Q_{rr} = f(di_F/dt)$

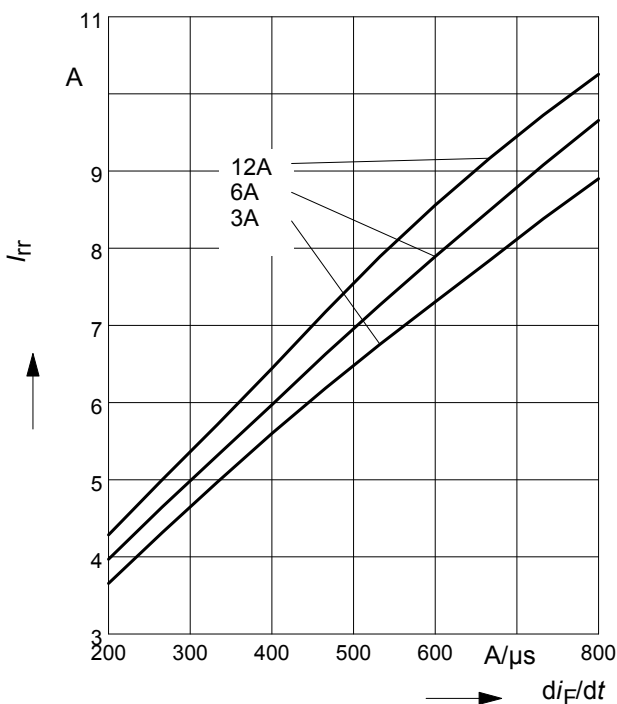
parameter: $V_R = 400V, T_j = 125^\circ C$



7 Typ. reverse recovery current

$I_{rr} = f(di_F/dt)$

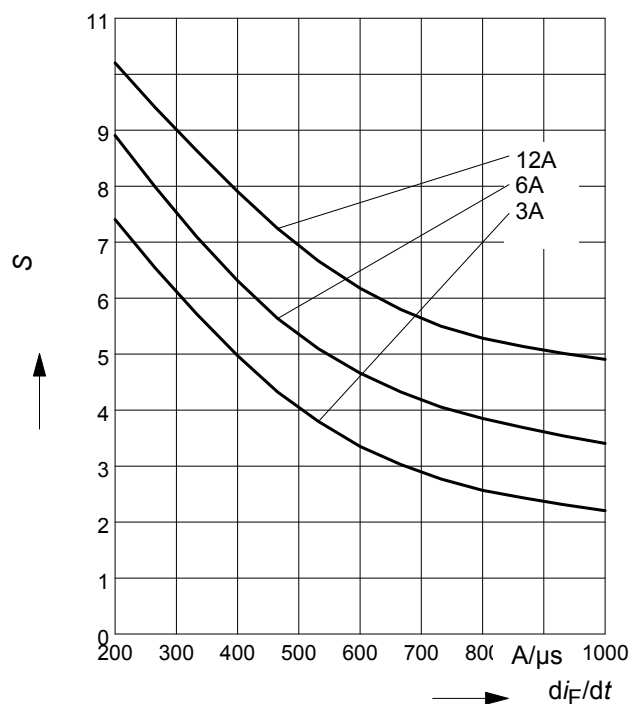
parameter: $V_R = 400V, T_j = 125^\circ C$



8 Typ. reverse recovery softness factor

$S = f(di_F/dt)$

parameter: $V_R = 400V, T_j = 125^\circ C$



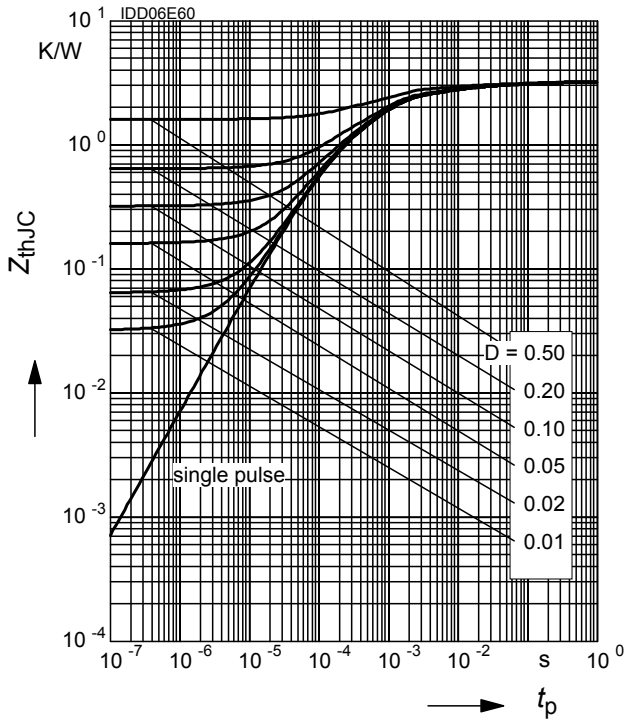


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9 Max. transient thermal impedance

$$Z_{thJC} = f(t_p)$$

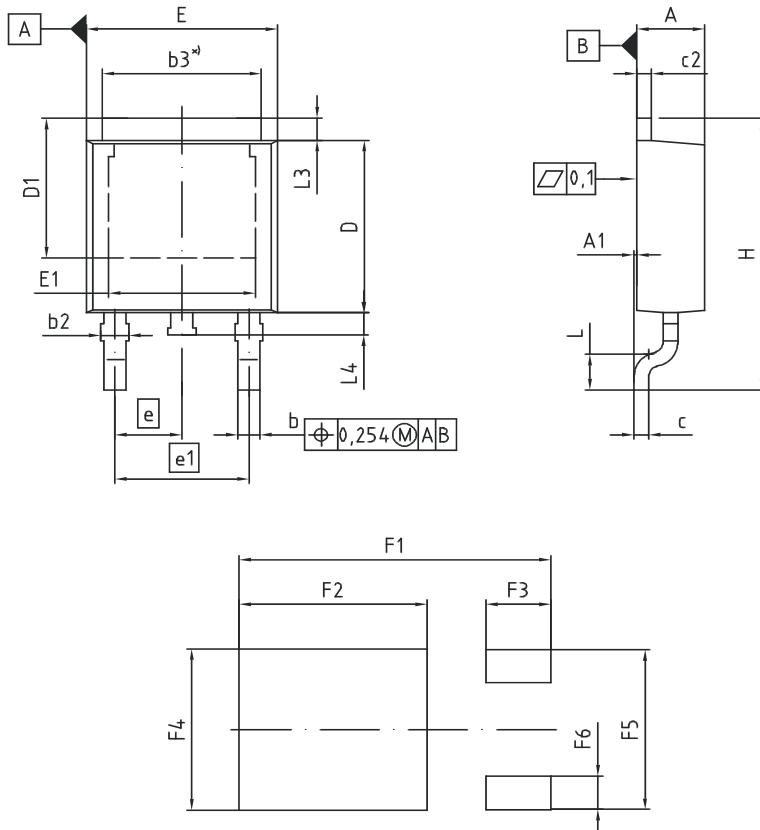
parameter : $D = t_p/T$





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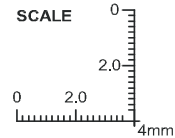
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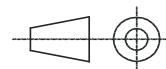
*) mold flash not included

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	2.16	2.41	0.085	0.095
A1	0.00	0.15	0.000	0.006
b	0.64	0.89	0.025	0.035
b2	0.65	1.15	0.026	0.045
b3	5.00	5.50	0.197	0.217
c	0.46	0.60	0.018	0.024
c2	0.46	0.98	0.018	0.039
D	5.97	6.22	0.235	0.245
D1	5.02	5.84	0.198	0.230
E	6.40	6.73	0.252	0.265
E1	4.70	5.21	0.185	0.205
e	2.29 (BSC)		0.090 (BSC)	
e1	4.57		0.180	
N	3		3	
H	9.40	10.48	0.370	0.413
L	1.18	1.70	0.046	0.067
L3	0.90	1.25	0.035	0.049
L4	0.51	1.00	0.020	0.039
F1	10.60		0.417	
F2	6.40		0.252	
F3	2.20		0.087	
F4	5.80		0.228	
F5	5.76		0.227	
F6	1.20		0.047	

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04



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